





160V NPN HIGH VOLTAGE TRANSISTOR PowerDI[®]5

Features

- 43% smaller than SOT223; 60% smaller than TO252
- Maximum height just 1.1mm
- Rated up to 2.25W
- V_{CEO} = 160V
- I_C = 0.6A
- Lead, Halogen and Antimony Free, RoHS Compliant (Note 1)
- "Green" Device (Note 2)

Applications

• Telecom line driver

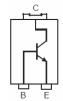
Mechanical Data

- Case: PowerDI[®]5
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin annealed over Copper leadframe.
 Solderable per MIL-STD-202, Method 208 [®]
- Weight: 0.093 grams (approximate)









Top View

Bottom View

Device Schematic

Pin-out diagram

Ordering Information (Note 3)

Part Number	Case	Packaging
DXT5551P5-13	PowerDI [®] 5	5000/Tape & Reel

Notes:

- 1. No purposefully added lead. Halogen and Antimony Free.
- 2. Diodes Inc's "Green" Policy can be found on our website at http://www.diodes.com
- 3. For packaging details, go to our website at http://www.diodes.com/datasheets/ap02007.pdf.

Marking Information



DXT5551 = Product Type Marking Code
DII = Manufacturers' Code Marking
K = Factory Designator
YYWW = Date Code Marking
YY = Last Two Digits of Year (ex: 09 for 2009)
WW = Week code 01 to 53





Maximum Ratings @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V_{CBO}	180	V
Collector-Emitter Voltage	V_{CEO}	160	V
Emitter-Base Voltage	V_{EBO}	6	V
Continuous Collector Current	lc	600	mA

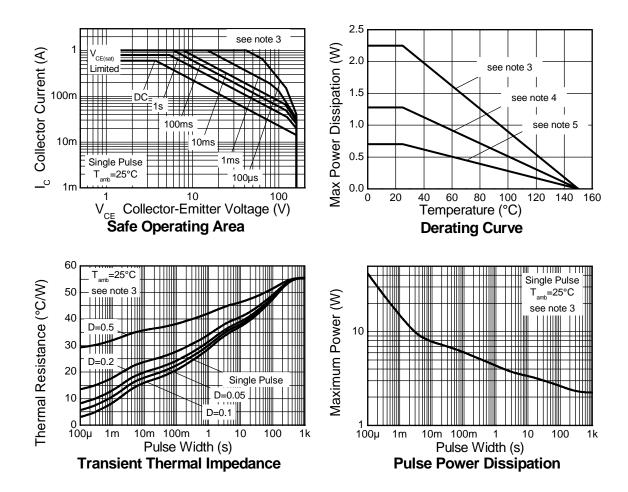
Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation @ T _A = 25°C (Note 4)	P_{D}	2.25	W
Thermal Resistance, Junction to Ambient Air (Note 4) @T _A = 25°C	$R_{ hetaJA}$	55.5	°C/W
Power Dissipation @ T _A = 25°C (Note 5)	P_{D}	1.28	W
Thermal Resistance, Junction to Ambient Air (Note 5) @T _A = 25°C	$R_{ hetaJA}$	97.4	°C/W
Power Dissipation @ T _A = 25°C (Note 6)	P_{D}	0.7	W
Thermal Resistance, Junction to Ambient Air (Note 6) @T _A = 25°C	$R_{ hetaJA}$	179	°C/W
Thermal Resistance, Junction to Collector Terminal	$R_{ heta JT}$	30	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

Notes:

- Device mounted on 1.6mm FR-4 PCB, single sided 2 oz. copper, collector pad dimensions 50mm x 50mm.
 Device mounted on 1.6mm FR-4 PCB, single sided 1 oz. copper, collector pad dimensions 25mm x 25mm.
 Device mounted on 1.6mm FR-4 PCB, single sided 1 oz. copper, minimum recommended pad layout.









Electrical Characteristics @T_A = 25°C unless otherwise specified

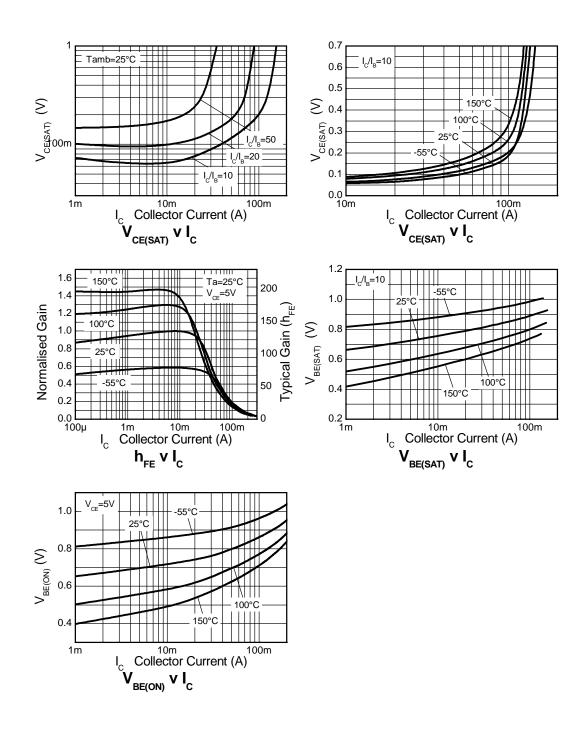
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Collector-Base Breakdown Voltage	V _{(BR)CBO}	180	270	ı	V	$I_C = 100 \mu A$
Collector-Emitter Breakdown Voltage (Note 7)	V _{(BR)CEO}	160	200	ı	V	I _C = 1mA
Emitter-Base Breakdown Voltage	$V_{(BR)EBO}$	6.0	7.85	Î	V	$I_E = 10\mu A$
Collector Cutoff Current	I _{CBO}	- -	<1 -	50 50	nA μA	V _{CB} = 120V V _{CB} = 120V, T _A = 100°C
Collector-Emitter Saturation Voltage (Note 7)	V _{CE(sat)}	- -	65 115	150 200	mV mV	$I_C = 10$ mA, $I_B = 1$ mA $I_C = 50$ mA, $I_B = 5$ mA
Base-Emitter Saturation Voltage (Note 7)	V _{BE(sat)}	- -	760 840	1000 1200	mV mV	$I_C = 10 \text{mA}, I_B = 1 \text{mA}$ $I_C = 50 \text{mA}, I_B = 5 \text{mA}$
DC Current Gain (Note 7)	h _{FE}	80 80 30	130 145 65	_ 250 _	-	$V_{CE} = 5V, I_{C} = 1mA$ $V_{CE} = 5V, I_{C} = 10mA$ $V_{CE} = 5V, I_{C} = 50mA$
Transition Frequency	f _T	-	130	-	MHz	$V_{CE} = 10V, I_{C} = 10mA,$ f = 100MHz
Output Capacitance (Note 7)	C_{obo}	_	-	6	pF	V _{CB} = 10V, f = 1MHz
Delay Time	t _(d)	-	95	-	ns	
Rise Time	t _(r)	-	64	-	Ns	$V_{CC} = 510V, I_{C} = 10mA,$
Storage Time	t _(s)	-	1256	ı	ns	$I_{B1} = I_{B2} = 1mA$
Delay Time	t _(f)	_	140	_	ns	

Notes: 7. Pulse Test: Pulse width $\leq 300 \mu s$. Duty cycle $\leq 2.0\%$.





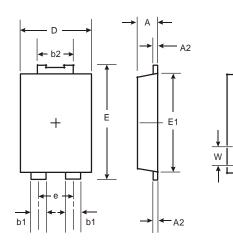
Typical Characteristic

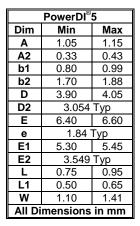






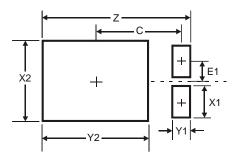
Package Outline Dimensions





E2

Suggested Pad Layout



Dimensions	Value (in mm)
Z	6.6
X1	1.4
X2	3.6
Y1	0.8
Y2	4.7
С	3.87
E1	0.0





IMPORTANT NOTICE

DIODES INCORPORATED MAKES NO WARRANTY OF ANY KIND, EXPRESS OR IMPLIED, WITH REGARDS TO THIS DOCUMENT, INCLUDING, BUT NOT LIMITED TO, THE IMPLIED WARRANTIES OF MERCHANTABILITY AND FITNESS FOR A PARTICULAR PURPOSE (AND THEIR EQUIVALENTS UNDER THE LAWS OF ANY JURISDICTION).

Diodes Incorporated and its subsidiaries reserve the right to make modifications, enhancements, improvements, corrections or other changes without further notice to this document and any product described herein. Diodes Incorporated does not assume any liability arising out of the application or use of this document or any product described herein; neither does Diodes Incorporated convey any license under its patent or trademark rights, nor the rights of others. Any Customer or user of this document or products described herein in such applications shall assume all risks of such use and will agree to hold Diodes Incorporated and all the companies whose products are represented on Diodes Incorporated website, harmless against all damages.

Diodes Incorporated does not warrant or accept any liability whatsoever in respect of any products purchased through unauthorized sales channel. Should Customers purchase or use Diodes Incorporated products for any unintended or unauthorized application, Customers shall indemnify and hold Diodes Incorporated and its representatives harmless against all claims, damages, expenses, and attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized application.

Products described herein may be covered by one or more United States, international or foreign patents pending. Product names and markings noted herein may also be covered by one or more United States, international or foreign trademarks.

LIFE SUPPORT

Diodes Incorporated products are specifically not authorized for use as critical components in life support devices or systems without the express written approval of the Chief Executive Officer of Diodes Incorporated. As used herein:

- A. Life support devices or systems are devices or systems which:
 - 1. are intended to implant into the body, or
 - 2. support or sustain life and whose failure to perform when properly used in accordance with instructions for use provided in the labeling can be reasonably expected to result in significant injury to the user.
- B. A critical component is any component in a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or to affect its safety or effectiveness.

Customers represent that they have all necessary expertise in the safety and regulatory ramifications of their life support devices or systems, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of Diodes Incorporated products in such safety-critical, life support devices or systems, notwithstanding any devices- or systems-related information or support that may be provided by Diodes Incorporated. Further, Customers must fully indemnify Diodes Incorporated and its representatives against any damages arising out of the use of Diodes Incorporated products in such safety-critical, life support devices or systems.

Copyright © 2010, Diodes Incorporated

www.diodes.com